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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/210,485	12/11/1998	PAUL MANSKY	65304-039	5370

7590 09/18/2003

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EXAMINER

WACHSMAN, HAL D

ART UNIT PAPER NUMBER

2857

DATE MAILED: 09/18/2003

Please find below and/or attached an Office communication concerning this application or proceeding.



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EXAMINER
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ART UNIT	PAPER
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42

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Commissioner for Patents

Hal D Wachsman  
Primary Examiner  
Art Unit: 2857

<b>Office Action Summary</b>	Application No. 09/210,485	Applicant(s) <i>fu</i> MANSKY ET AL.	
	Examiner Hal D Wachsman	Art Unit 2857	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 25 June 2003.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 1-6,8-10,13-17,19-21,23-25,113-133 and 135-156 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☒ Claim(s) 113-133,135-152,155 and 156 is/are allowed.
- 6) ☒ Claim(s) 1-6,8,13-17,19-21,23,24,153 and 154 is/are rejected.
- 7) ☒ Claim(s) 9,10 and 25 is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 27 February 2002 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) ☐ The proposed drawing correction filed on \_\_\_\_\_ is: a) ☐ approved b) ☐ disapproved by the Examiner.  
If approved, corrected drawings are required in reply to this Office action.
- 12) ☐ The oath or declaration is objected to by the Examiner.

**Priority under 35 U.S.C. §§ 119 and 120**

- 13) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
a) ☐ All   b) ☐ Some \* c) ☐ None of:  
1. ☐ Certified copies of the priority documents have been received.  
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.  
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).  
\* See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).  
a) ☐ The translation of the foreign language provisional application has been received.
- 15) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

**Attachment(s)**

- |   |   |
|---|---|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892)  | 4) <input type="checkbox"/> Interview Summary (PTO-413) Paper No(s). _____  |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)                          | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO-1449) Paper No(s) <u>39</u> . | 6) <input type="checkbox"/> Other: _____                                    |

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 6-25-03 has been entered.
2. The terminal disclaimer filed on 6-25-03 disclaiming the terminal portion of any patent granted on this application which would extend beyond the expiration date of U.S. patent no. 6,477,479 has been reviewed and is accepted. The terminal disclaimer has been recorded.
3. The "Notification of Reasons for Refusal dated January 21, 2003" cited on the IDS filed 6-25-03, has not been considered because what is cited on this document is not prior art.
4. Claims 4, 8-10, 13-17, 19-21, 23-25, 131, 143 and 151 are objected to under 37 C.F.R. 1.75(a) for failing to particularly point out and distinctly claim the subject matter which the applicant regards as the invention. Claim 4, lines 10-11, cite "said at least one thermal property of said 5 or more samples" which it appears should be "said at least one thermal property of said one of said 5 or more samples". Claim 8, line 2, cites "the thermal property" however the antecedent basis is "at least one thermal property". Claim 131, line 2, has what appears to be a strike through line above the comma after "121" however was the comma here intended to be deleted by the strike through line ? This same type of problem also occurs in claim 143, line 2, and claim 151, line 1. The

examiner asks the applicant to better claim the limitations cited above. While the examiner understands the intentions of the applicant he feels confusion could be drawn from the limitations cited above. Appropriate correction is required.

***Claim Rejections - 35 USC § 103***

5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

6. Claims 1, 8, 13-17 and 19-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lewis et al. (5,788,833) in view of Kimura Mitsuteru (JP 10-260147).

As per claim 1, Lewis et al.'833 (Abstract, figure 1B, col. 2 lines 18-34, 47-53, col. 10 lines 6-11, col. 11 lines 7-11, col. 17 lines 61-67, col. 18 lines 1-18, col. 20

lines 14-23) disclose the substrate as described in lines 3-5 of the claim. Lewis et al.'833 (Abstract, figure 1C, col. 2 lines 47-58, col. 8 lines 4-15) disclose the interconnection device as described in line 6 of the claim. Lewis et al.'833 (figure 1C, col. 8 lines 5-15, 53-61, col. 10 lines 6-11, 15-62, col. 11 lines 7-11) disclose the electronic platform as described in the last 6 lines of the claim with the exception of clearly disclosing "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". However, Kimura Mitsuteru (see translation – Abstract, claim 1, paragraphs 0010, 0012, 0035, 0040, 0042) teaches this excepted feature. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kimura Mitsuteru to the invention of Lewis et al.'833 as specified above because as taught by Kumura Mitsuteru (Abstract, paragraph 0009) a sample in a trace mount can then be heated by a heater whose heat capacity is small, and the sample can be heated to a high temperature by very small electric power, providing high-speed response with minute power.

As per claim 8, Lewis et al.'833 (col. 9 lines 34-67, col. 10 lines 1-14, col. 19 lines 57-67, col. 20 lines 1-23) disclose at least one of the thermal properties from the group in this claim.

As per claim 13, Lewis et al.'833 (col. 13 lines 7-10, col. 17 lines 10-25, col. 20 lines 4-23) disclose the feature of this claim.

As per claim 14, Lewis et al.'833 (col. 17 – table 4, col. 19 lines 58-60) disclose the feature of this claim.

As per claim 15, Lewis et al.'833 (col. 7 lines 43-65) disclose the feature of this claim.

As per claim 16, Lewis et al.'833 (col. 13 lines 7-10, col. 17 lines 10-25, col. 20 lines 4-23) disclose the feature of this claim.

As per claim 17, Lewis et al.'833 (col. 7 lines 43-65) disclose the feature of this claim.

As per claim 19, Lewis et al.'833 (Abstract, figures 1A – 1, 1A, col. 2 lines 24-26, col. 5, table 2, col. 6 lines 25-32) disclose the feature of this claim.

As per claim 20, Lewis et al.'833 (col. 7 lines 40-42, col. 9 lines 49-67, col. 19 lines 62-67, col. 20 lines 1-16) disclose the feature of this claim.

As per claim 21, Lewis et al.'833 (col. 7 lines 40-42) disclose the feature of this claim.

7. Claims 2-6, 8, 13-17 and 19-21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lewis et al. (5,788,833) in view of Kimura Mitsuteru (JP 10-260147) and Lewis (6,170,318).

As per claim 2, Lewis et al.'833 (Abstract, figure 1B, col. 2 lines 18-34, 47-53, col. 10 lines 6-11, col. 11 lines 7-11, col. 17 lines 61-67, col. 18 lines 1-18, col. 20 lines 14-23) disclose the substrate as described in lines 3-5 of the claim. Lewis et al.'833 (figure 1C, col. 8 lines 5-15, 53-61, col. 10 lines 6-11, 15-62, col. 11 lines 7-11) disclose the signal routing means with the exception of explicitly disclosing that a circuit board is being used to couple the signal routing means to the sensor array and that the circuit board is coupled to the sensor array and disclose the electronic platform as

described in the last 8 lines of the claim with the exception of clearly disclosing “a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate”. However, Kimura Mitsuteru (see translation – Abstract, claim 1, paragraphs 0010, 0012, 0035, 0040, 0042) teaches this excepted feature. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kimura Mitsuteru to the invention of Lewis et al.’833 as specified above because as taught by Kimura Mitsuteru (Abstract, paragraph 0009) a sample in a trace mount can then be heated by a heater whose heat capacity is small, and the sample can be heated to a high temperature by very small electric power, providing high-speed response with minute power. It appears the above combination of references still does not explicitly teach that a circuit board is being used to couple the signal routing means to the sensor array and that the circuit board is coupled to the sensor array. However, Lewis’318 (col. 12 lines 1-5, 65-67, col. 13 lines 21-26) teaches these excepted features. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Lewis’318 to the invention of Lewis et al.’833 and Kimura Mitsuteru as specified above because as taught by Lewis’318 (col. 13 lines 23-26) the sensor density on the chip must be increased for hand-held type applications from that of box-type applications and this can be achieved using PCB technology.

As per claim 3, Lewis et al.’833 (Abstract, figure 1B, col. 2 lines 18-34, 47-53, col. 10 lines 6-11, col. 11 lines 7-11, col. 17 lines 61-67, col. 18 lines 1-18, col. 20



lines 14-23) disclose the substrate as described in lines 3-5 of the claim. Lewis et al.'833 (figure 1C, col. 8 lines 5-15, 53-61, col. 10 lines 6-11, 15-62, col. 11 lines 7-11) disclose the electronic platform as described in the last 8 lines of the claim with the exception of clearly disclosing "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". In addition, Lewis et al.'833 does not clearly disclose the circuit board as described in lines 6-7 of the claim. However, Kimura Mitsuteru (see translation – Abstract, claim 1, paragraphs 0010, 0012, 0035, 0040, 0042) teaches "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kimura Mitsuteru to the invention of Lewis et al.'833 as specified above because as taught by Kimura Mitsuteru (Abstract, paragraph 0009) a sample in a trace mount can then be heated by a heater whose heat capacity is small, and the sample can be heated to a high temperature by very small electric power, providing high-speed response with minute power. It appears though that the above combination of references still does not clearly teach the circuit board as described in lines 6-7 of the claim. However, Lewis'318 (col. 12 lines 1-5, 65-67, col. 13 lines 21-26) teaches this excepted feature. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Lewis'318 to the invention of Lewis et al.'833 and Kimura Mitsuteru as specified above because as taught by Lewis'318 (col. 13 lines 23-26) the sensor density on the chip

must be increased for hand-held type applications from that of box-type applications and this can be achieved using PCB technology.

As per claim 4, Lewis et al.'833 (Abstract, figure 1B, col. 2 lines 18-34, 47-53, col. 10 lines 6-11, col. 11 lines 7-11, col. 17 lines 61-67, col. 18 lines 1-18, col. 20 lines 14-23) disclose the substrate as described in lines 3-5 of the claim. Lewis et al.'833 (figure 1C, col. 8 lines 5-15, 53-61, col. 10 lines 6-11, 15-62, col. 11 lines 7-11) disclose the remaining features of this claim with the exception of those features being placed on a circuit board and "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". However, Kimura Mitsuteru (see translation – Abstract, claim 1, paragraphs 0010, 0012, 0035, 0040, 0042) teaches "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kimura Mitsuteru to the invention of Lewis et al.'833 as specified above because as taught by Kimura Mitsuteru (Abstract, paragraph 0009) a sample in a trace mount can then be heated by a heater whose heat capacity is small, and the sample can be heated to a high temperature by very small electric power, providing high-speed response with minute power. It appears though that the above combination of references still does not clearly teach the features being placed on a circuit board. However, Lewis'318 (col. 12 lines 1-5, 65-67, col. 13 lines 21-26) teaches this excepted feature. It would have been obvious to a person of ordinary skill in the art

at the time the invention was made to apply the techniques of Lewis'318 to the invention of Lewis et al.'833 and Kimura Mitsuteru as specified above because as taught by Lewis'318 (col. 13 lines 23-26) the sensor density on the chip must be increased for hand-held type applications from that of box-type applications and this can be achieved using PCB technology.

As per claim 5, Lewis et al.'833 (Abstract, figure 1B, col. 2 lines 18-34, col. 17 lines 61-67, col. 18 lines 1-18) disclose the plurality of sensors as described in lines 4-6 of the claim. Lewis et al.'833 (figure 1C, col. 8 lines 5-15, 53-61, col. 10 lines 15-62, col. 11 lines 61-67) disclose the signal routing means, the electronic test circuitry as described in lines 8-11 of the claim and the computer for controlling as described in the last 6 lines of the claim with the exception of clearly disclosing "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". In addition, Lewis et al.'833 does not explicitly disclose that all these features have been placed on a circuit board. However, Kimura Mitsuteru (see translation – Abstract, claim 1, paragraphs 0010, 0012, 0035, 0040, 0042) teaches "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kimura Mitsuteru to the invention of Lewis et al.'833 as specified above because as taught by Kimura Mitsuteru (Abstract, paragraph 0009) a sample in a trace mount can then be heated by a heater whose heat capacity is small,

and the sample can be heated to a high temperature by very small electric power, providing high-speed response with minute power. It appears that the above combination features though still does not clearly teach the circuit board. However, Lewis'318 (col. 12 lines 1-5, 65-67, col. 13 lines 21-26) teaches this excepted feature. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Lewis'318 to the invention of Lewis et al.'833 and Kimura Mitsuteru as specified above because as taught by Lewis'318 (col. 13 lines 23-26) the sensor density on the chip must be increased for hand-held type applications from that of box-type applications and this can be achieved using PCB technology.

As per claim 6, Lewis et al.'833 (Abstract, figure 1B, col. 2 lines 18-34, col. 17 lines 61-67, col. 18 lines 1-18) disclose the plurality of sensors as described in lines 4-6 of the claim. Lewis et al.'833 (figure 1C, col. 8 lines 5-15, 53-61, col. 10 lines 15-62, col. 11 lines 61-67) disclose the signal routing means, the electronic test circuitry as described in lines 9-11 of the claim and the computer for controlling as described in the last 6 lines of the claim with the exception of clearly disclosing "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". In addition, Lewis et al.'833 does not explicitly disclose that all these features have been placed on a circuit board. However, Kimura Mitsuteru (see translation – Abstract, claim 1, paragraphs 0010, 0012, 0035, 0040, 0042) teaches "a plurality of thermometers disposed on a top surface of said substrate, and wherein said substrate includes a large area heater disposed on a bottom surface of said substrate". It would have been

obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kimura Mitsuteru to the invention of Lewis et al.'833 as specified above because as taught by Kimura Mitsuteru (Abstract, paragraph 0009) a sample in a trace mount can then be heated by a heater whose heat capacity is small, and the sample can be heated to a high temperature by very small electric power, providing high-speed response with minute power. It appears that the above combination features though still does not clearly teach the circuit board. However, Lewis'318 (col. 12 lines 1-5, 65-67, col. 13 lines 21-26) teaches this excepted feature. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Lewis'318 to the invention of Lewis et al.'833 and Kimura Mitsuteru as specified above because as taught by Lewis'318 (col. 13 lines 23-26) the sensor density on the chip must be increased for hand-held type applications from that of box-type applications and this can be achieved using PCB technology.

As per claim 8, Lewis et al.'833 (col. 9 lines 34-67, col. 10 lines 1-14, col.19 lines 57-67, col. 20 lines 1-23) disclose at least one of the thermal properties from the group in this claim.

As per claim 13, Lewis et al.'833 (col. 13 lines 7-10, col. 17 lines 10-25, col. 20 lines 4-23) disclose the feature of this claim.

As per claim 14, Lewis et al.'833 (col. 17 – table 4, col. 19 lines 58-60) disclose the feature of this claim.

As per claim 15, Lewis et al.'833 (col. 7 lines 43-65) disclose the feature of this claim.

As per claim 16, Lewis et al.'833 (col. 13 lines 7-10, col. 17 lines 10-25, col. 20 lines 4-23) disclose the feature of this claim.

As per claim 17, Lewis et al.'833 (col. 7 lines 43-65) disclose the feature of this claim.

As per claim 19, Lewis et al.'833 (Abstract, figures 1A – 1, 1A, col. 2 lines 24-26, col. 5, table 2, col. 6 lines 25-32) disclose the feature of this claim.

As per claim 20, Lewis et al.'833 (col. 7 lines 40-42, col. 9 lines 49-67, col. 19 lines 62-67, col. 20 lines 1-16) disclose the feature of this claim.

As per claim 21, Lewis et al.'833 (col. 7 lines 40-42) disclose the feature of this claim.

8. Claims 23 and 24 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lewis et al. (5,788,833) in view of Kimura Mitsuteru (JP 10-260147) as applied to claim 1 above, and further in view of "Dielectric Monitoring of Polymerization and Cure" (Kranbuehl).

As per claim 23, Kranbuehl (pages 303-305) teaches the feature of this claim. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kranbuehl to the inventions of Lewis et al.'833 and Kimura Mitsuteru as specified above because as taught by Kranbuehl (page 303) frequency dependent dielectric measurements have become an effective instrumental means for monitoring a variety of polymer resin processing properties.

As per claim 24, Lewis et al.'833 (Figures 1A-1, 1B) disclose the feature of this claim.

9. Claims 23, 24, 153 and 154 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lewis et al.'833 in view of Kimura Mitsuteru (JP 10-260147) and Lewis (6,170,318) as applied to claims 2, 3 or 4 above, and further in view of "Dielectric Monitoring of Polymerization and Cure" (Kranbuehl).

As per claim 23, Kranbuehl (pages 303-305) teaches the feature of this claim. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kranbuehl to the inventions of Lewis et al.'833, Kimural Mitsuteru and Lewis'318 as specified above because as taught by Kranbuehl (page 303) frequency dependent dielectric measurements have become an effective instrumental means for monitoring a variety of polymer resin processing properties.

As per claim 24, Lewis et al.'833 (Figures 1A-1, 1B) disclose the feature of this claim.

As per claim 153, Lewis et al.'833 (col. 9 lines 34-67, col. 10 lines 1-14, col.19 lines 57-67, col. 20 lines 1-23) disclose at least one of the thermal properties from the group in this claim.

As per claim 154, Kranbuehl (pages 303-305) teaches the feature of this claim. It would have been obvious to a person of ordinary skill in the art at the time the invention was made to apply the techniques of Kranbuehl to the inventions of Lewis et al.'833, Kimural Mitsuteru and Lewis'318 as specified above because as taught by Kranbuehl (page 303) frequency dependent dielectric measurements have become an

effective instrumental means for monitoring a variety of polymer resin processing properties.

10. Claims 113-133, 135-152, 155 and 156 are allowed subject to the appropriate correction of the 37 C.F.R. 1.75(a) objections noted in paragraph 4 above.

Claims 9, 10 and 25 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims and subject to the appropriate correction of the 37 C.F.R. 1.75(a) objections noted above.


11. Applicant's arguments with respect to the claims have been considered but are moot in view of the new ground(s) of rejection.

12. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hal D Wachsman whose telephone number is 703-305-9788. The examiner can normally be reached on Monday to Friday 7:00 A.M. to 4:30 P.M..

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Marc Hoff can be reached on 703-308-1677. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.



Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

  
Hal D Wachsman  
Primary Examiner  
Art Unit 2857

HW  
September 13, 2003